

P-Ch 20V Fast Switching MOSFETs

Description

The IRLML2246TR is the high cell density trenched P-ch MOSFETs, which provides excellent RDSON and efficiency for most of the small power switching and load switch applications.

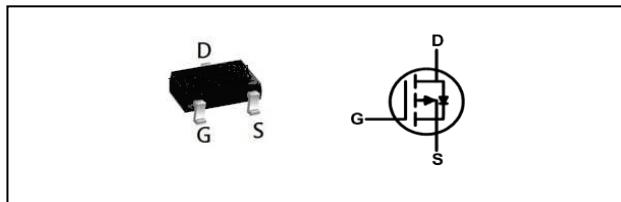
The IRLML2246TR meet the RoHS and Green Product requirement with full function reliability approved.

Product Summary

V_{DS}	-20	V
$R_{DS(ON),typ}$	89	$m\Omega$
I_D	-3	A

- Green Device Available
- Super Low Gate Charge
- Excellent C_{dv}/dt effect decline
- Advanced high cell density Trench technology

SOT23 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-3	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-2.4	A
I_{DM}	Pulsed Drain Current ²	-12	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation ³	1	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	125	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	80	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

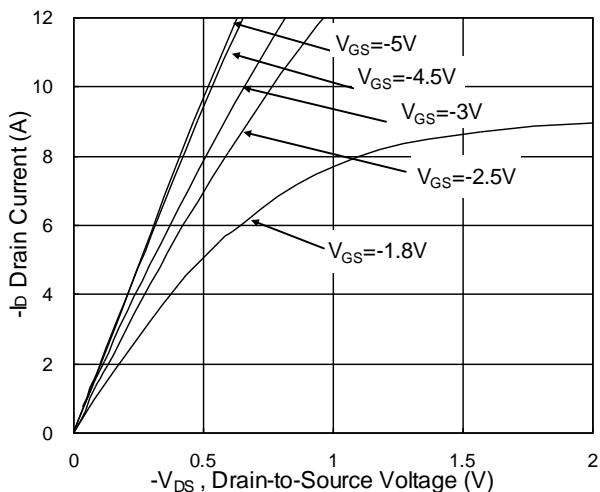
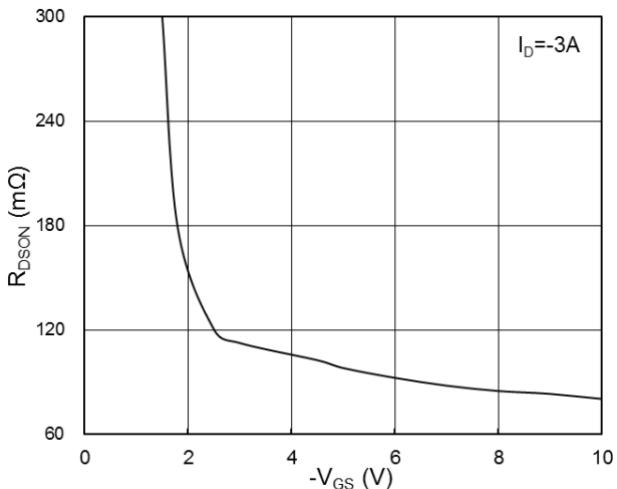
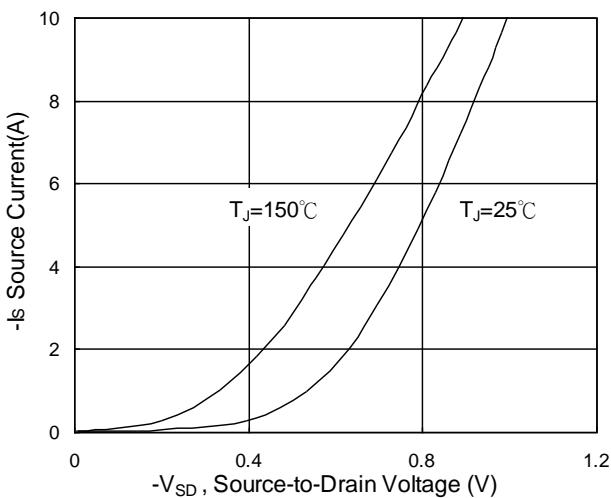
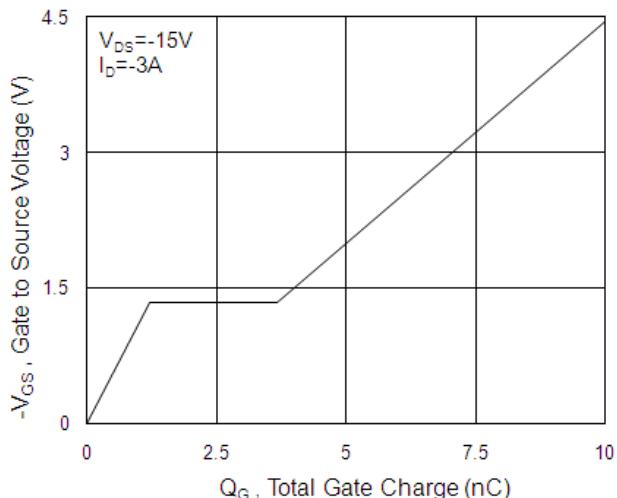
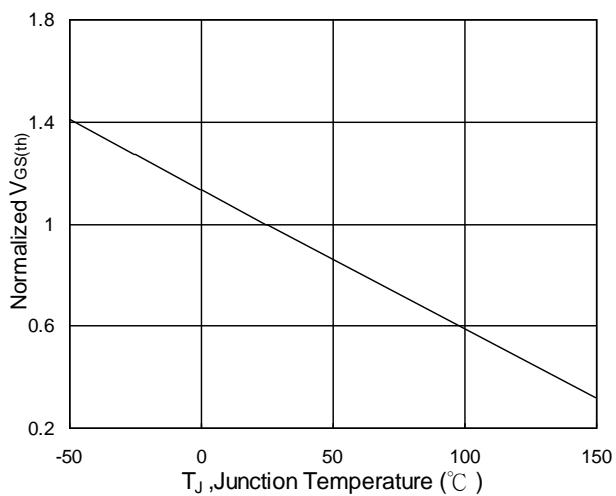
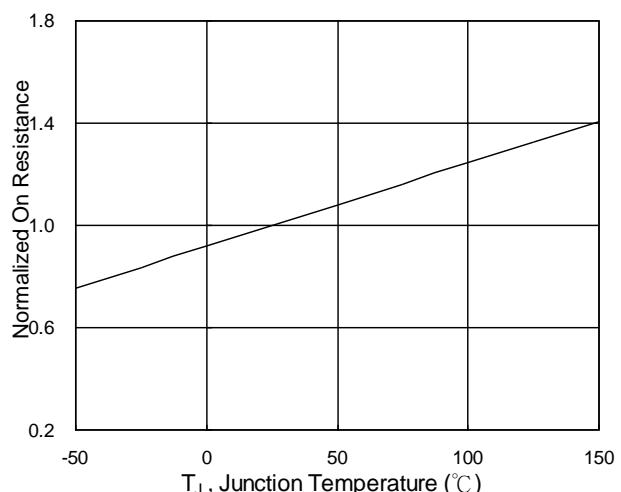
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-20	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-3\text{A}$	---	89	100	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$, $I_{\text{D}}=-2\text{A}$	---	130	140	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=-250\mu\text{A}$	-0.3	-0.5	-1.0	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	uA
		$V_{\text{DS}}=-16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$, $I_{\text{D}}=-3\text{A}$	---	12.2	---	S
Q_g	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-3\text{A}$	---	10.1	---	nC
Q_{gs}	Gate-Source Charge		---	1.21	---	
Q_{gd}	Gate-Drain Charge		---	2.46	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $R_{\text{G}}=3.3\Omega$	---	5.6	---	ns
T_r	Rise Time		---	32.2	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	45.6	---	
T_f	Fall Time		---	29.2	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	677	---	pF
C_{oss}	Output Capacitance		---	82	---	
C_{rss}	Reverse Transfer Capacitance		---	73	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,4}	$V_G=V_D=0\text{V}$, Force Current	---	---	-3	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics**Fig.1 Typical Output Characteristics****Fig.2 On-Resistance vs. G-S Voltage****Fig.3 Source Drain Forward Characteristics****Fig.4 Gate-Charge Characteristics****Fig.5 Normalized $V_{GS(th)}$ vs. T_J** **Fig.6 Normalized $R_{DS(on)}$ vs. T_J**

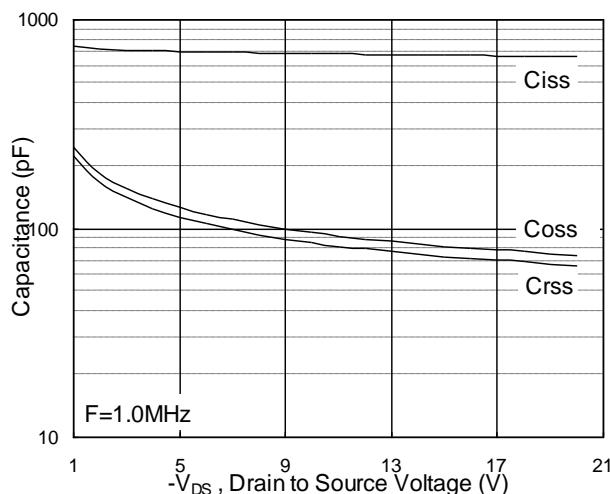


Fig.7 Capacitance

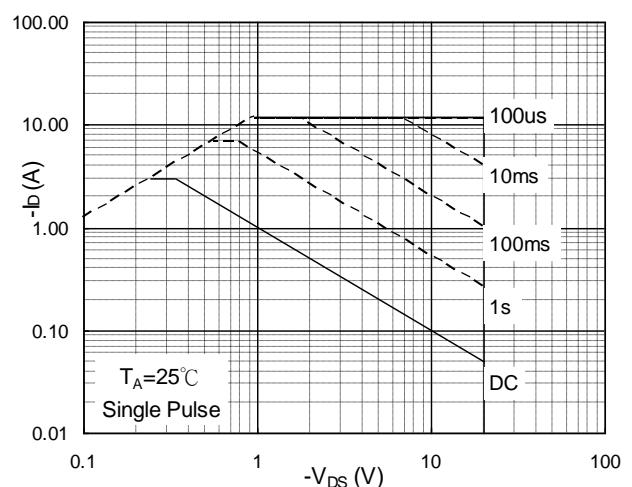


Fig.8 Safe Operating Area

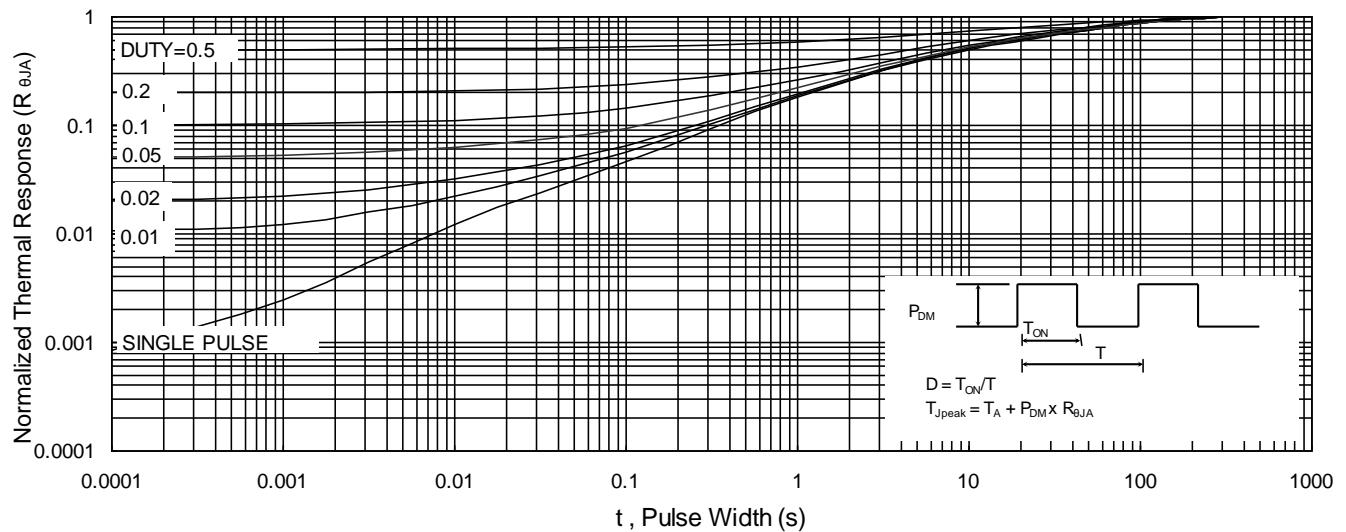


Fig.9 Normalized Maximum Transient Thermal Impedance

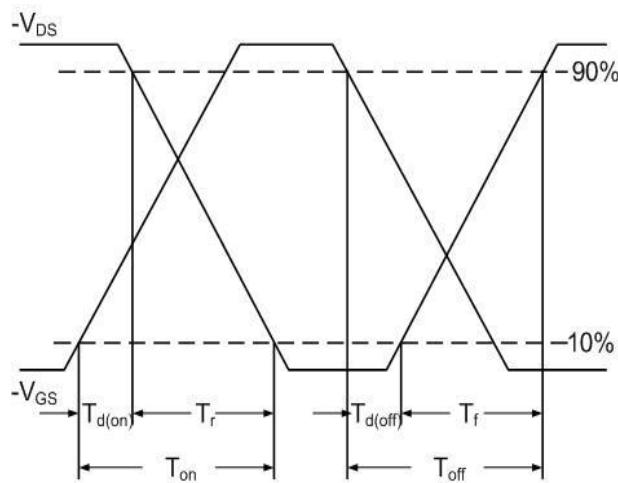


Fig.10 Switching Time Waveform

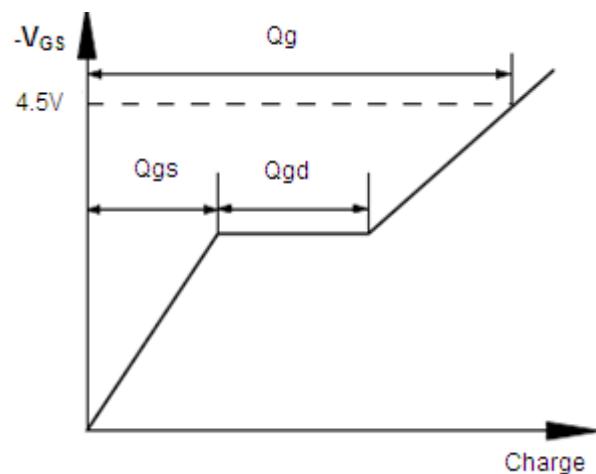
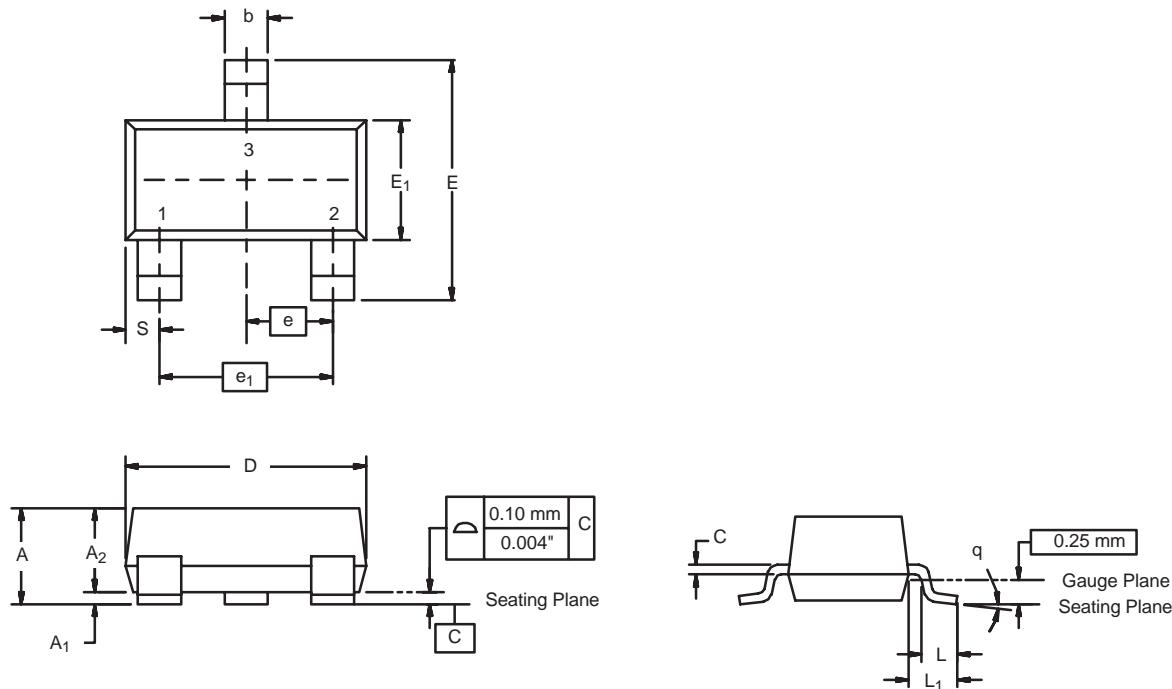


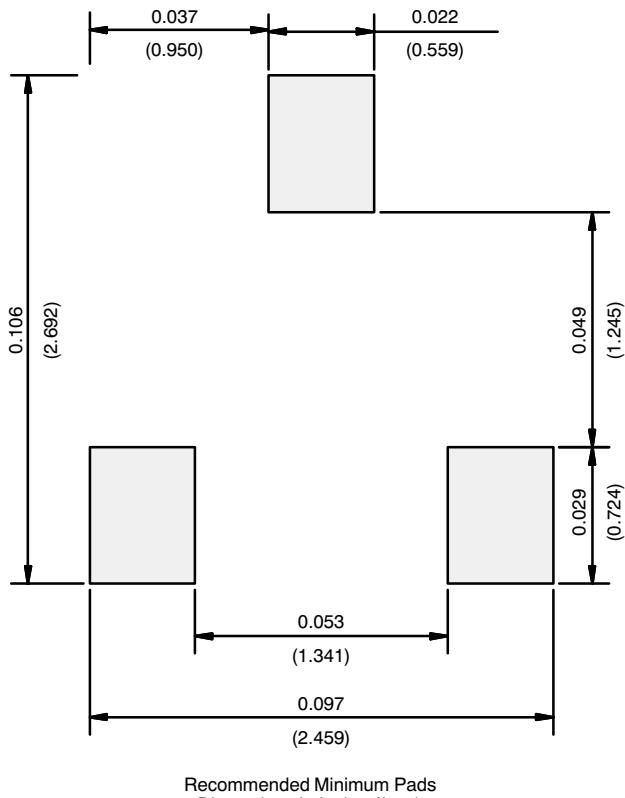
Fig.11 Gate Charge Waveform

SOT-23 (TO-236): 3-LEAD

Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.89	1.12	0.035	0.044
A ₁	0.01	0.10	0.0004	0.004
A ₂	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
c	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E ₁	1.20	1.40	0.047	0.055
e	0.95 BSC		0.0374 Ref	
e ₁	1.90 BSC		0.0748 Ref	
L	0.40	0.60	0.016	0.024
L ₁	0.64 Ref		0.025 Ref	
S	0.50 Ref		0.020 Ref	
q	3°	8°	3°	8°

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DWG: 5479

RECOMMENDED MINIMUM PADS FOR SOT-23

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